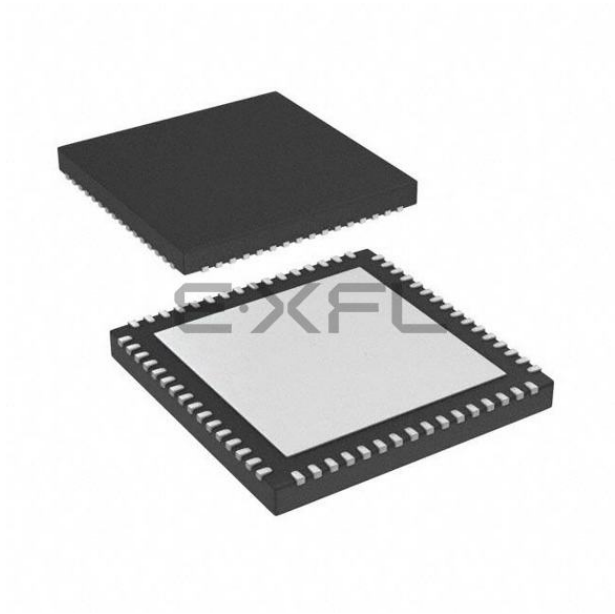
Microchip Technology - PIC32MX350F128HT-V/RG Datasheet



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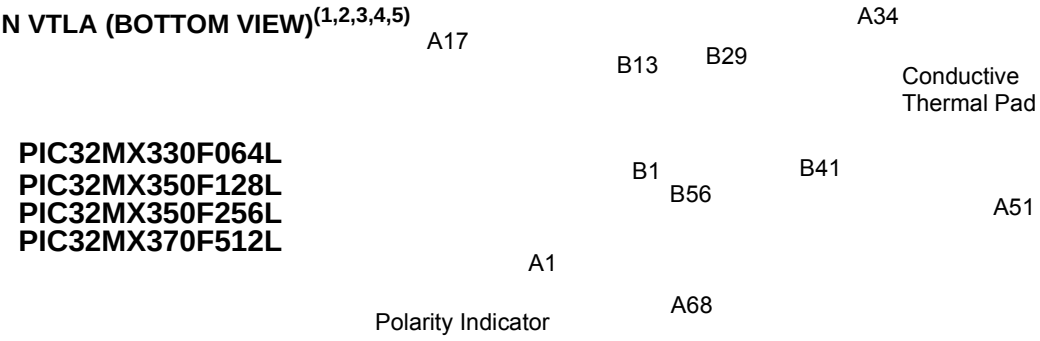
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx350f128ht-v-rg

TABLE 6: PIN NAMES FOR 124-PIN DEVICES (CONTINUED)

124-PIN VTLA (BOTTOM VIEW)(1,2,3,4,5)



Package Bump #	Full Pin Name	Package Bump #	Full Pin Name
B7	$\overline{MCLR}$	B32	SDA2/RA3
B8	VSS	B33	TDO/RA5
B9	TMS/CTED1/RA0	B34	OSC1/CLKI/RC12
B10	RPE9/RE9	B35	No Connect
B11	AN4/C1INB/RB4	B36	RPA14/RA14
B12	VSS	B37	RPD8/RTCC/RD8
B13	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	B38	RPD10/PMCS2/RD10
B14	PGED1/AN0/RPB0/RB0	B39	RPD0/RD0
B15	No Connect	B40	SOSCO/RPC14/T1CK/RC14
B16	PGED2/AN7/RPB7/CTED3/RB7	B41	VSS
B17	VREF+/CVREF+/PMA6/RA10	B42	AN25/RPD2/RD2
B18	AVSS	B43	RPD12/PMD12/RD12
B19	AN9/RPB9/CTED4/RB9	B44	RPD4/PMWR/RD4
B20	AN11/PMA12/RB11	B45	PMD14/RD6
B21	VDD	B46	No Connect
B22	RPF13/RF13	B47	No Connect
B23	AN12/PMA11/RB12	B48	VCAP
B24	AN14/RPB14/CTED5/PMA1/RB14	B49	RPF0/PMD11/RF0
B25	VSS	B50	RPG1/PMD9/RG1
B26	RPD14/RD14	B51	TRCLK/RA6
B27	RPF4/PMA9/RF4	B52	PMD0/RE0
B28	No Connect	B53	VDD
B29	RPF8/RF8	B54	TRD2/RG14
B30	RPF6/SCKI/INT0/RF6	B55	TRD0/RG13
B31	SCL1/RG2	B56	RPE3/CTPLS/PMD3/RE3

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx), with the exception of RF6, can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

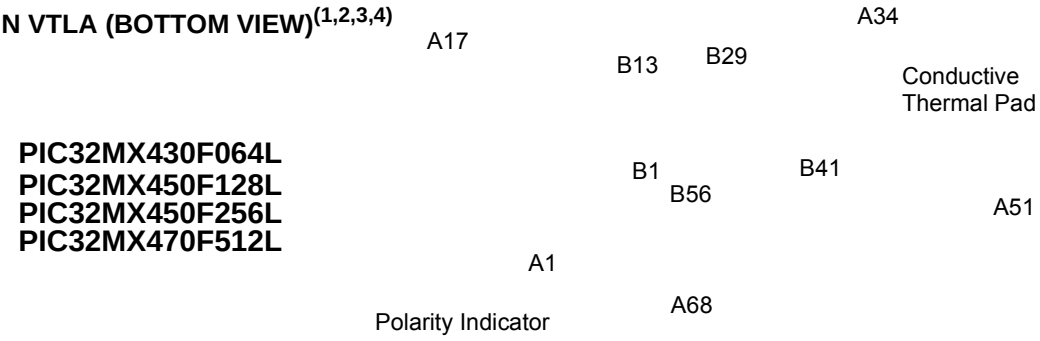
3: RPF6 (bump B30) and RPF7 (bump A37) are only remappable for input functions.

4: Shaded package bumps are 5V tolerant.

5: It is recommended that the user connect the printed circuit board (PCB) ground to the conductive thermal pad on the bottom of the package. And to not run non-Vss PCB traces under the conductive thermal pad on the same side of the PCB layout.

TABLE 7: PIN NAMES FOR 124-PIN DEVICES (CONTINUED)

124-PIN VTLA (BOTTOM VIEW)(1,2,3,4)



Package Bump #	Full Pin Name	Package Bump #	Full Pin Name
B7	$\overline{MCLR}$	B32	SDA2/RA3
B8	VSS	B33	TDO/RA5
B9	TMS/CTED1/RA0	B34	OSC1/CLKI/RC12
B10	RPE9/RE9	B35	No Connect
B11	AN4/C1INB/RB4	B36	SCL1/RPA14/RA14
B12	VSS	B37	RPD8/RTCC/RD8
B13	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	B38	RPD10/SCK1/PMCS2/RD10
B14	PGED1/AN0/RPB0/RB0	B39	RPD0/INT0/RD0
B15	No Connect	B40	SOSCO/RPC14/T1CK/RC14
B16	PGED2/AN7/RPB7/CTED3/RB7	B41	VSS
B17	VREF+/CVREF+/PMA6/RA10	B42	AN25/RPD2/RD2
B18	AVSS	B43	RPD12/PMD12/RD12
B19	AN9/RPB9/CTED4/RB9	B44	RPD4/PMWR/RD4
B20	AN11/PMA12/RB11	B45	PMD14/RD6
B21	VDD	B46	No Connect
B22	RPF13/RF13	B47	No Connect
B23	AN12/PMA11/RB12	B48	VCAP
B24	AN14/RPB14/CTED5/PMA1/RB14	B49	RPF0/PMD11/RF0
B25	VSS	B50	RPG1/PMD9/RG1
B26	RPD14/RD14	B51	TRCLK/RA6
B27	RPF4/PMA9/RF4	B52	PMD0/RE0
B28	No Connect	B53	VDD
B29	RPF8/RF8	B54	TRD2/RG14
B30	VUSB3V3	B55	TRD0/RG13
B31	D+	B56	RPE3/CTPLS/PMD3/RE3

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: Shaded package bumps are 5V tolerant.

4: It is recommended that the user connect the printed circuit board (PCB) ground to the conductive thermal pad on the bottom of the package. And to not run non-Vss PCB traces under the conductive thermal pad on the same side of the PCB layout.

1.0 DEVICE OVERVIEW

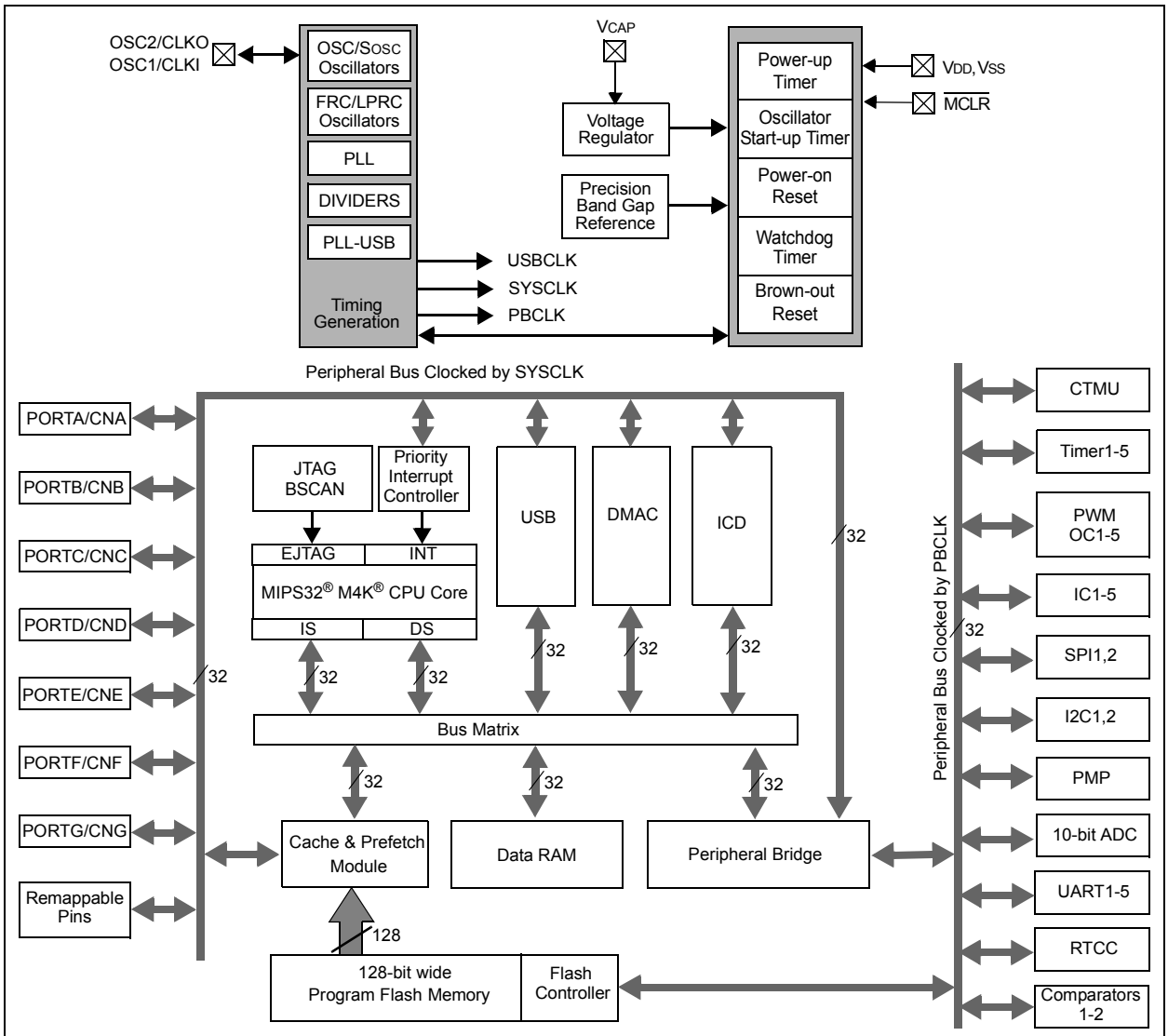
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This document contains device-specific information for PIC32MX330/350/370/430/450/470 devices.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the PIC32MX330/350/370/430/450/470 family of devices.

Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: PIC32MX330/350/370/430/450/470 BLOCK DIAGRAM



Note: Not all features are available on all devices. Refer to **TABLE 1: "PIC32MX330/350/370/430/450/470 Controller Family Features"** for the list of features by device.

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- CIN = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- COUT = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}] \} + \text{estimated oscillator PCB stray capacitance}$$
$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5] \} + 2.5\ pF$$
$$= \{([20][20]) / [40] \} + 2.5$$
$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 13 pF in this example for Primary Oscillator crystals “C1” and “C2”.

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

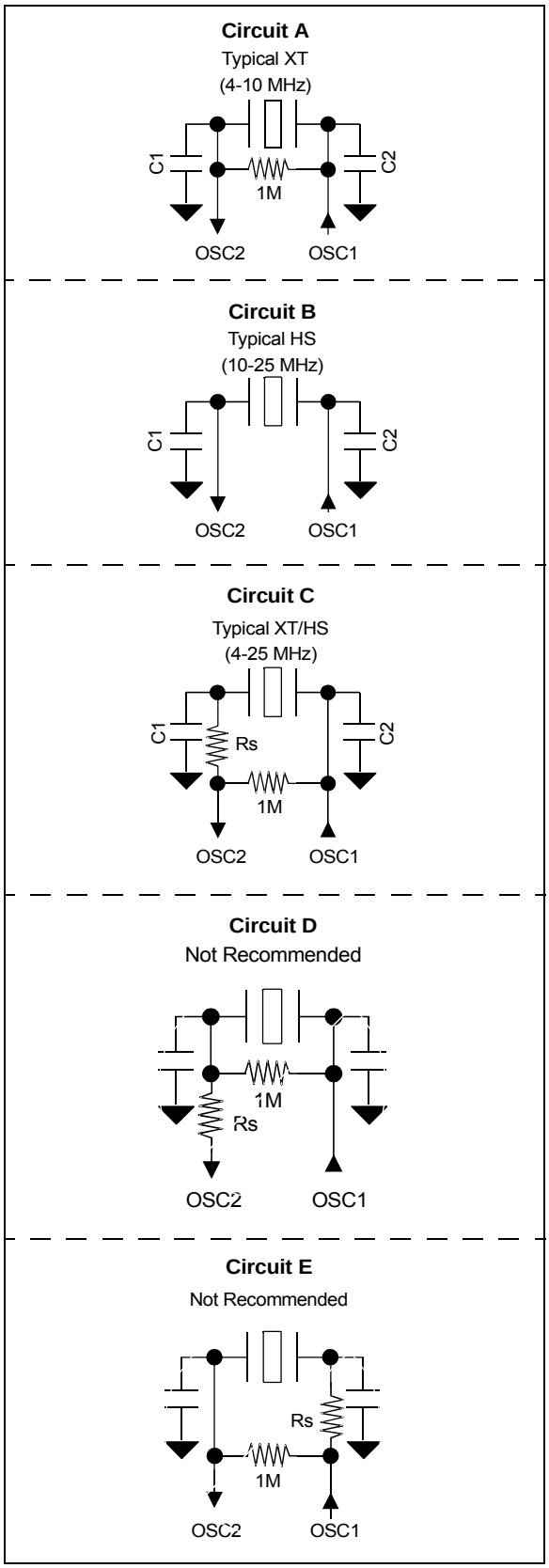
- Select a crystal with a lower “minimum” power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing “ESR” rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

Note: Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit “C” in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~VDD-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

- AN588 *“PICmicro® Microcontroller Oscillator Design Guide”*
- AN826 *“Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices”*
- AN849 *“Basic PICmicro® Oscillator Design”*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS



7.1 Interrupts Control Registers

TABLE 7-2: INTERRUPT REGISTER MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	FCEIF	RTCCIF	FSCMIF	AD1IF	OC5IF	IC5IF	IC5EIF	T5IF	INT4IF	OC4IF	IC4IF	IC4EIF	T4IF	INT3IF	OC3IF	IC3IF	0000
		15:0	IC3EIF	T3IF	INT2IF	OC2IF	IC2IF	IC2EIF	T2IF	INT1IF	OC1IF	IC1IF	IC1EIF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	U3RXIF	U3EIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2TXIF	SPI2RXIF	SPI2EIF	PMPEIF	PMPIF	CNGIF	CNFIF	CNEIF	0000
		15:0	CNDIF	CNCIF	CNBIF	CNAIF	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	SPI1TXIF	SPI1RXIF	SPI1EIF	USBIF(2)	CMP2IF	CMP1IF	0000
1050	IFS2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	DMA3IF	DMA2IF	DMA1IF	DMA0IF	CTMUIF	U5TXIF(1)	U5RXIF(1)	U5EIF(1)	U4TXIF	U4RXIF	U4EIF	U3TXIF	0000
1060	IEC0	31:16	FCEIE	RTCCIE	FSCMIE	AD1IE	OC5IE	IC5IE	IC5EIE	T5IE	INT4IE	OC4IE	IC4IE	IC4EIE	T4IE	INT3IE	OC3IE	IC3IE	0000
		15:0	IC3EIE	T3IE	INT2IE	OC2IE	IC2IE	IC2EIE	T2IE	INT1IE	OC1IE	IC1IE	IC1EIE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	U3RXIE	U3EIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2TXIE	SPI2RXIE	SPI2EIE	PMPEIE	PMPIE	CNGIE	CNFIE	CNEIE	0000
		15:0	CNDIE	CNCIE	CNBIE	CNAIE	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	SPI1TXIE	SPI1RXIE	SPI1EIE	USBIE(2)	CMP2IE	CMP1IE	0000
1080	IEC2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	DMA3IE	DMA2IE	DMA1IE	DMA0IE	CTMUIE	U5TXIE(1)	U5RXIE(1)	U5EIE(1)	U4TXIE	U4RXIE	U4EIE	U3TXIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>		—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>		—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>		—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>		—	—	—	T5IP<2:0>			T5IS<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This bit is only available on 100-pin devices.

2: This bit is only implemented on devices with a USB module.

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	R/W-y	R/W-y	R/W-y	R/W-0	R/W-0	R/W-1
	—	—	PLLODIV<2:0>			FRCDIV<2:0>		
23:16	U-0	R-0	R-1	R/W-y	R/W-y	R/W-y	R/W-y	R/W-y
	—	SOSCRDY	PBDIVRDY	PBDIV<1:0>		PLLMULT<2:0>		
15:8	U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
	—	COSC<2:0>			—	NOSC<2:0>		
7:0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-y	R/W-0
	CLKLOCK	ULOCK(1)	SLOCK	SLPEN	CF	UFRCEN(1)	SOSCEN	OSWEN

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-30 **Unimplemented:** Read as '0'

bit 29-27 **PLLODIV<2:0>:** Output Divider for PLL
- 111 = PLL output divided by 256
- 110 = PLL output divided by 64
- 101 = PLL output divided by 32
- 100 = PLL output divided by 16
- 011 = PLL output divided by 8
- 010 = PLL output divided by 4
- 001 = PLL output divided by 2
- 000 = PLL output divided by 1

bit 26-24 **FRCDIV<2:0>:** Internal Fast RC (FRC) Oscillator Clock Divider bits
- 111 = FRC divided by 256
- 110 = FRC divided by 64
- 101 = FRC divided by 32
- 100 = FRC divided by 16
- 011 = FRC divided by 8
- 010 = FRC divided by 4
- 001 = FRC divided by 2 (default setting)
- 000 = FRC divided by 1

bit 23 **Unimplemented:** Read as '0'

bit 22 **SOSCRDY:** Secondary Oscillator (SOSC) Ready Indicator bit
- 1 = Indicates that the Secondary Oscillator is running and is stable
- 0 = Secondary Oscillator is still warming up or is turned off

bit 21 **PBDIVRDY:** Peripheral Bus Clock (PBCLK) Divisor Ready bit
- 1 = PBDIV<1:0> bits can be written
- 0 = PBDIV<1:0> bits cannot be written

bit 20-19 **PBDIV<1:0>:** Peripheral Bus Clock (PBCLK) Divisor bits
- 11 = PBCLK is SYSCLK divided by 8 (default)
- 10 = PBCLK is SYSCLK divided by 4
- 01 = PBCLK is SYSCLK divided by 2
- 00 = PBCLK is SYSCLK divided by 1

Note 1: This bit is available on PIC32MX4XX devices only.

Note: Writes to this register require an unlock sequence. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

REGISTER 11-11: U1CON: USB CONTROL REGISTER (CONTINUED)

bit 1 **PPBRST:** Ping-Pong Buffers Reset bit
1 = Reset all Even/Odd buffer pointers to the EVEN BD banks
0 = Even/Odd buffer pointers not being Reset

bit 0 **USBEN:** USB Module Enable bit(4)
1 = USB module and supporting circuitry is enabled
0 = USB module and supporting circuitry is disabled

SOFEN: SOF Enable bit(5)
1 = SOF token sent every 1 ms
0 = SOF token is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 11-15).

2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set the RESUME bit for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a low-speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

5: Host mode.

REGISTER 11-18: U1BDTP2: USB BDT PAGE 2 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRH<23:16>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRH<23:16>:** BDT Base Address bits

This 8-bit value provides address bits 23 through 16 of the BDT base address, which defines the starting location of the BDT in system memory.

The 32-bit BDT base address is 512-byte aligned.

REGISTER 11-19: U1BDTP3: USB BDT PAGE 3 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRU<31:24>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRU<31:24>:** BDT Base Address bits

This 8-bit value provides address bits 31 through 24 of the BDT base address, defines the starting location of the BDT in system memory.

The 32-bit BDT base address is 512-byte aligned.

TABLE 12-13: PORTF REGISTER MAP FOR PIC32MX330F064H, PIC32MX350F128H, PIC32MX350F256H, AND PIC32MX370F512H DEVICES ONLY

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6510	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	xxxx
6520	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	RF6	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6530	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	LATF6	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6540	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	ODCF6	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	xxxx
6550	CNPUF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	CNPUF6	CNPUF5	CNPUF4	CNPUF3	CNPUF2	CNPUF1	CNPUF0	xxxx
6560	CNPDF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	CNPDF6	CNPDF5	CNPDF4	CNPDF3	CNPDF2	CNPDF1	CNPDF0	xxxx
6570	CNCONF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6580	CNENF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	CNIEF5	CNIEF4	CNIEF3	CNIEF2	CNIEF1	CNIEF0	xxxx
6590	CNSTATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	CN STATF5	CN STATF4	CN STATF3	CN STATF2	CN STATF1	CN STATF0	xxxx

Legend: x = Unknown value on Reset; — = Unimplemented, read as '0'; Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

NOTES:

REGISTER 18-1: SPIxCON: SPI CONTROL REGISTER (CONTINUED)

bit 4 **DISSDI:** Disable SDI bit
1 = SDI pin is not used by the SPI module (pin is controlled by PORT function)
0 = SDI pin is controlled by the SPI module

bit 3-2 **STXISEL<1:0>:** SPI Transmit Buffer Empty Interrupt Mode bits
11 = Interrupt is generated when the buffer is not full (has one or more empty elements)
10 = Interrupt is generated when the buffer is empty by one-half or more
01 = Interrupt is generated when the buffer is completely empty
00 = Interrupt is generated when the last transfer is shifted out of SPISR and transmit operations are complete

bit 1-0 **SRXISEL<1:0>:** SPI Receive Buffer Full Interrupt Mode bits
11 = Interrupt is generated when the buffer is full
10 = Interrupt is generated when the buffer is full by one-half or more
01 = Interrupt is generated when the buffer is not empty
00 = Interrupt is generated when the last word in the receive buffer is read (i.e., buffer is empty)

Note 1: When using the 1:1 PBCLK divisor, the user software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit can only be written when the ON bit = 0.

3: This bit is not used in the Framed SPI mode. The user should program this bit to '0' for the Framed SPI mode (FRMEN = 1).

4: When AUDEN = 1, the SPI module functions as if the CKP bit is equal to '1', regardless of the actual value of CKP.

REGISTER 18-3: SPIxSTAT: SPI STATUS REGISTER (CONTINUED)

bit 3 **SPITBE:** SPI Transmit Buffer Empty Status bit
1 = Transmit buffer, SPIxTXB is empty
0 = Transmit buffer, SPIxTXB is not empty
Automatically set in hardware when SPI transfers data from SPIxTXB to SPIxSR.
Automatically cleared in hardware when SPIxBUF is written to, loading SPIxTXB.

bit 2 **Unimplemented:** Read as '0'

bit 1 **SPITBF:** SPI Transmit Buffer Full Status bit
1 = Transmit not yet started, SPITXB is full
0 = Transmit buffer is not full
Standard Buffer Mode:
Automatically set in hardware when the core writes to the SPIBUF location, loading SPITXB.
Automatically cleared in hardware when the SPI module transfers data from SPITXB to SPISR.
Enhanced Buffer Mode:
Set when CWPTR + 1 = SRPTR; cleared otherwise

bit 0 **SPIRBF:** SPI Receive Buffer Full Status bit
1 = Receive buffer, SPIxRXB is full
0 = Receive buffer, SPIxRXB is not full
Standard Buffer Mode:
Automatically set in hardware when the SPI module transfers data from SPIxSR to SPIxRXB.
Automatically cleared in hardware when SPIxBUF is read from, reading SPIxRXB.
Enhanced Buffer Mode:
Set when SWPTR + 1 = CRPTR; cleared otherwise

REGISTER 23-4: AD1CHS: ADC INPUT SELECT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CH0NB	—	—	CH0SB<4:0>				
23:16	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CH0NA(3)	—	—	CH0SA<4:0>				
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **CH0NB:** Negative Input Select bit for Sample B
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VREFL

bit 30-29 **Unimplemented:** Read as '0'

bit 28-24 **CH0SB<4:0>:** Positive Input Select bits for Sample B
11110 = Channel 0 positive input is Open(1)
11101 = Channel 0 positive input is CTMU temperature sensor (CTMUT)(2)
11100 = Channel 0 positive input is IVREF(3)
11011 = Channel 0 positive input is AN27
•
•
•
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

bit 23 **CH0NA:** Negative Input Select bit for Sample A Multiplexer Setting(3)
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VREFL

bit 22-21 **Unimplemented:** Read as '0'

bit 20-16 **CH0SA<4:0>:** Positive Input Select bits for Sample A Multiplexer Setting
11110 = Channel 0 positive input is Open(1)
11101 = Channel 0 positive input is CTMU temperature sensor (CTMUT)(2)
11100 = Channel 0 positive input is IVREF(3)
11011 = Channel 0 positive input is AN27
•
•
•
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

bit 15-0 **Unimplemented:** Read as '0'

Note 1: This selection is only used with CTMU capacitive and time measurement.
2: See **Section 26.0 "Charge Time Measurement Unit (CTMU)"** for more information.
3: See **Section 25.0 "Comparator Voltage Reference (CVREF)"** for more information.

25.1 Control Register

TABLE 25-1: COMPARATOR VOLTAGE REFERENCE REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9800	CVRCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	—	—	—	—	—	—	CVROE	CVRR	CVRSS	CVR<3:0>				0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: The register in this table has corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

TABLE 31-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	**Typ.(2)**	**Max.**	**Units**	**Conditions**	
PIC32MX350F256 Devices Only					
Power-Down Current (IPD) (Note 1)					
DC40k	38	80	µA	-40°C	Base Power-Down Current
DC40l	57	80	µA	+25°C	
DC40n	220	352	µA	+85°C	
DC40m	513	749	µA	+105ºC	
PIC32MX450F256 Devices Only					
Power-Down Current (IPD) (Note 1)					
DC40k	26	42	µA	-40°C	Base Power-Down Current
DC40o	26	42	µA	0°C(5)	
DC40l	26	42	µA	+25°C	
DC40p	250	352	µA	+70°C(5)	
DC40n	250	352	µA	+85°C	
DC40m	513	749	µA	+105ºC	

Note 1: The test conditions for IPD measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, program Flash memory Wait states = 7, Program Cache and Prefetch are disabled and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- RTCC and JTAG are disabled
- Voltage regulator is off during Sleep mode (VREGS bit in the RCON register = 0)

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: 120 MHz commercial devices only (0ºC to +70ºC).

TABLE 31-19: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	3.92	—	5	MHz	ECPLL, HSPLL, XTPLL, FRCPLL modes
OS51a	FSYS	On-Chip VCO System Frequency	60	—	120	MHz	Commercial devices
OS51b			60	—	100	MHz	Industrial devices
OS51c			60	—	80	MHz	V-temp devices
OS52	TLOCK	PLL Start-up Time (Lock Time)	—	—	2	ms	—
OS53	DCLK	CLKO Stability(2) (Period Jitter or Cumulative)	-0.25	—	+0.25	%	Measured over 100 ms period

Note 1: These parameters are characterized, but not tested in manufacturing.

2: This jitter specification is based on clock-cycle by clock-cycle measurements. To get the effective jitter for individual time-bases on communication clocks, use the following formula:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{SYSCLK}{CommunicationClock}}}$$

For example, if SYSCLK = 40 MHz and SPI bit rate = 20 MHz, the effective jitter is as follows:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{40}{20}}} = \frac{D_{CLK}}{1.41}$$

TABLE 31-20: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
Internal FRC Accuracy @ 8.00 MHz(1)						
F20b	FRC	-0.9	—	+0.9	%	—

Note 1: Frequency calibrated at 25°C and 3.3V. The TUN bits can be used to compensate for temperature drift.

TABLE 31-34: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE) (CONTINUED)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250		ns	
IS40	TAA:SCL	Output Valid from Clock	100 kHz mode	0	3500	ns	—
			400 kHz mode	0	1000	ns	
			1 MHz mode **(Note 1)**	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode **(Note 1)**	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	—

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

FIGURE 32-13: TYPICAL IDD CURRENT @ VDD = 3.3V

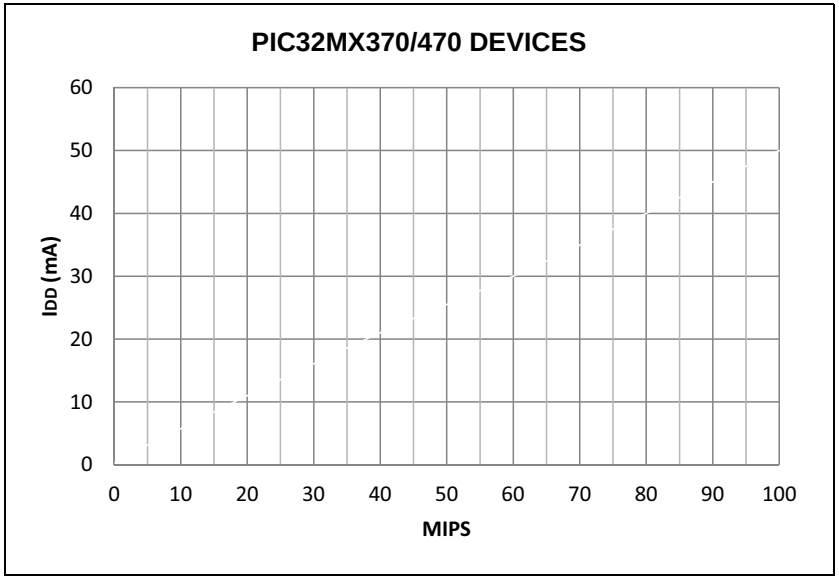


FIGURE 32-14: TYPICAL FRC FREQUENCY @ VDD = 3.3V

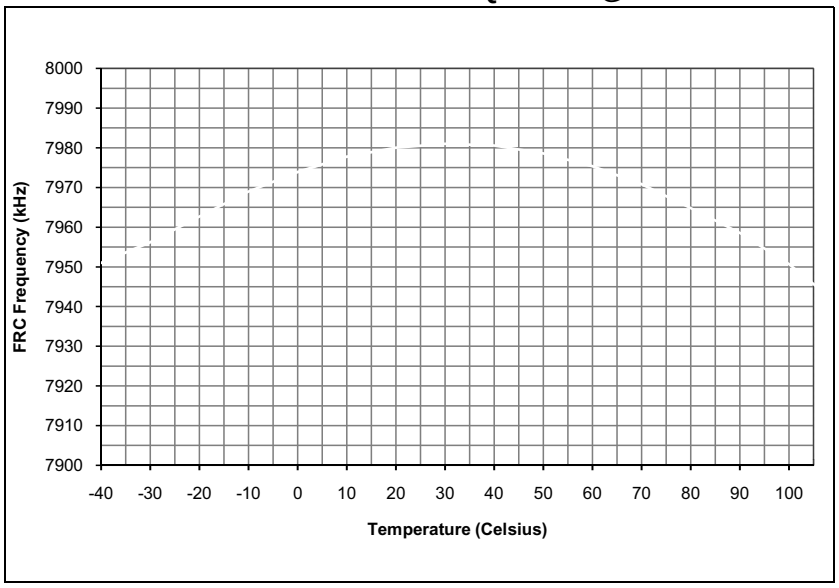


FIGURE 32-15: TYPICAL LPRC FREQUENCY @ VDD = 3.3V

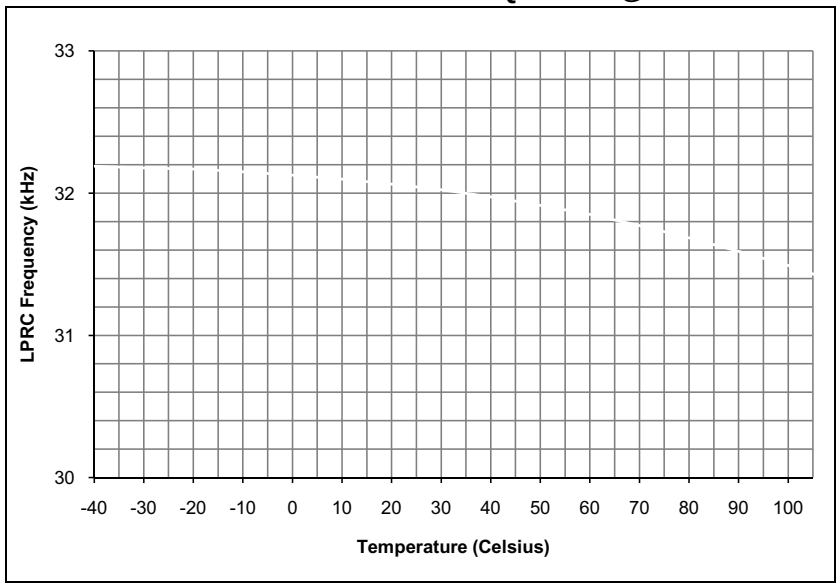
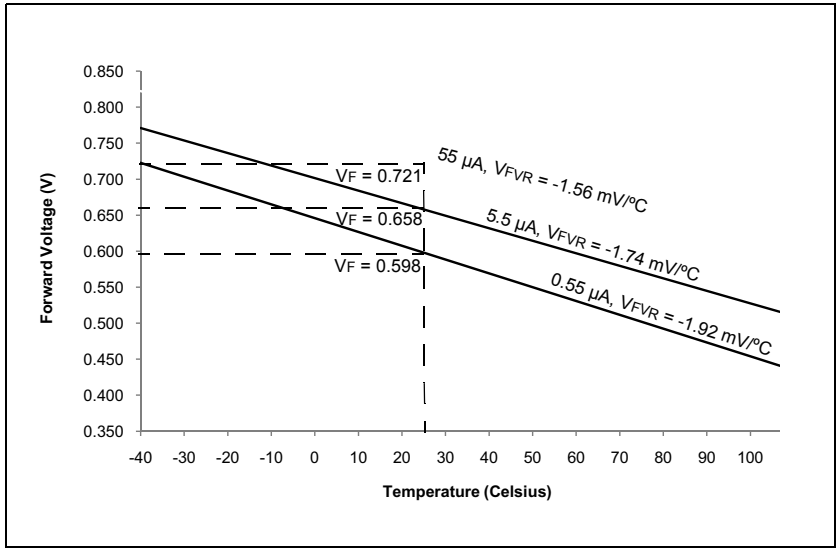
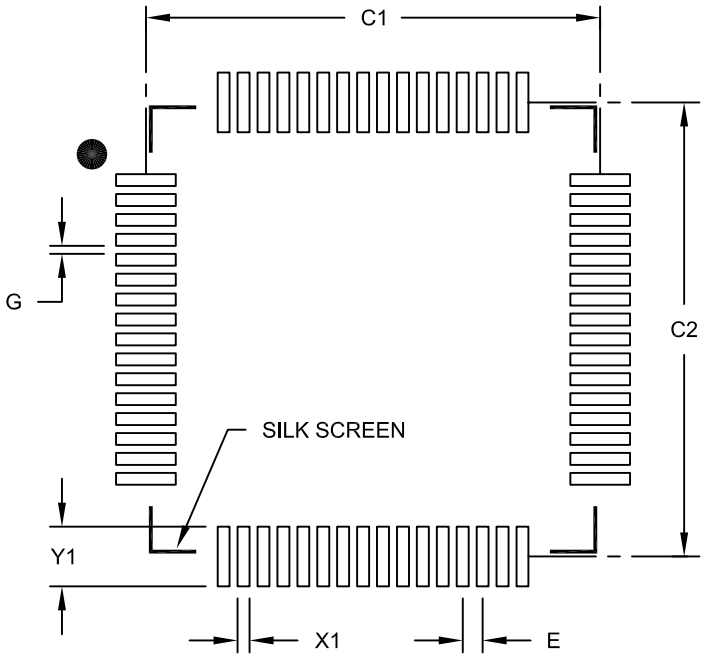


FIGURE 32-16: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE



64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

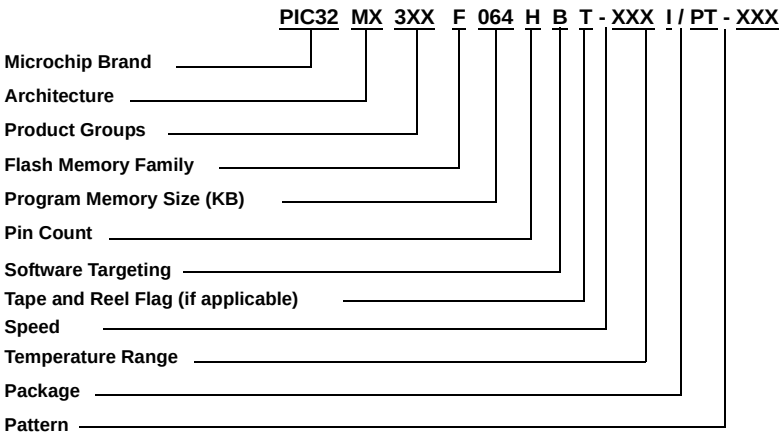
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Example:

PIC32MX330F064H-I/PT:
General purpose PIC32,
32-bit RISC MCU,
64 KB program memory,
64-pin, Industrial temperature,
TQFP package.

Flash Memory Family

Architecture	MX = 32-bit RISC MCU core
Product Groups	3XX = General purpose microcontroller family 4XX = General purpose with USB microcontroller family
Flash Memory Family	F = Flash program memory
Program Memory Size	064 = 6 4KB 128 = 128KB 256 = 256KB 512 = 512KB
Pin Count	H = 64-pin L = 100-pin
Software Targeting	B = Targeted for Bluetooth Audio Break-in devices
Speed	blank = up to 100 MHz 120 = up to 120 MHz
Temperature Range	blank = 0°C to +70°C (Commercial) I = -40°C to +85°C (Industrial) V = -40°C to +105°C (V-Temp)
Package	MR = 64-Lead (9x9x0.9 mm) QFN with 5.40x5.40 Exposed Pad (Plastic Quad Flat) RG = 64-Lead (9x9x0.9 mm) QFN with 4.7x4.7 Exposed Pad (Plastic Quad Flat) PT = 64-Lead (10x10x1 mm) TQFP (Thin Quad Flatpack) PT = 100-Lead (12x12x1 mm) TQFP (Thin Quad Flatpack) PF = 100-Lead (14x14x1 mm) TQFP (Thin Quad Flatpack) TL = 124-Lead (9x9x0.9 mm) VTLA (Very Thin Leadless Array)
Pattern	Three-digit QTP, SQTP, Code or Special Requirements (blank otherwise) ES = Engineering Sample